

DOCUMENT TYPE: PLP

DOCUMENT ID #: 90-100270

REVISION: B-000

DOCUMENT TITLE: PACKAGE LAND PATTERN, [K3255Y+12C] SAWN

EFFECTIVE DATE: 05/13/2024

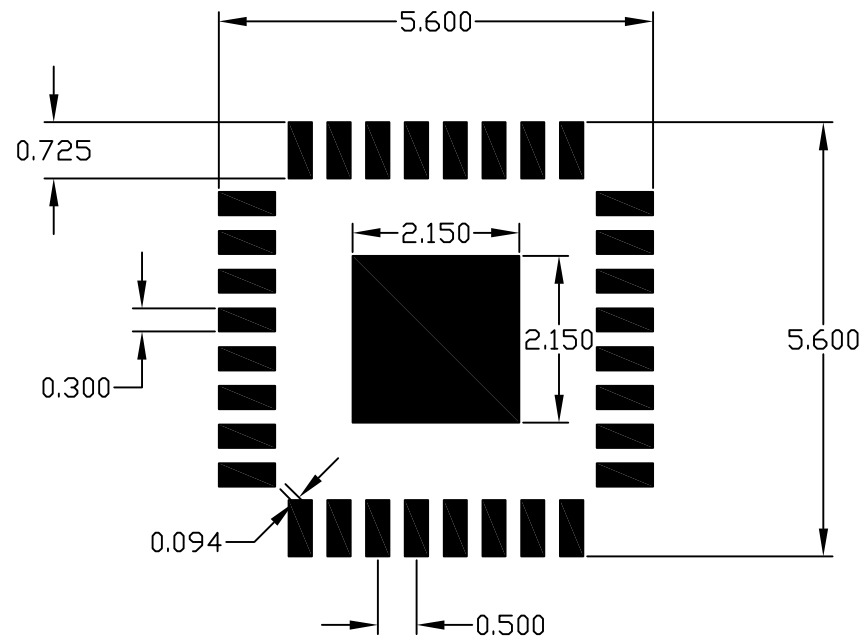
EXPIRATION DATE:

CHANGE NUMBER: 1209450

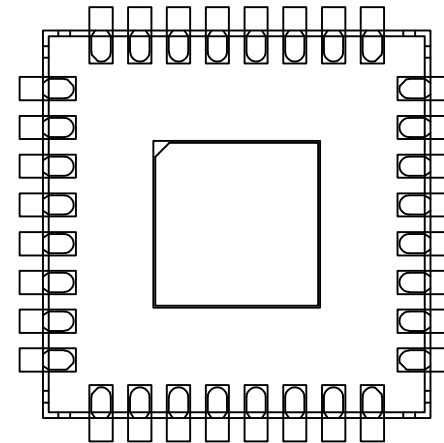
ORIGINATOR: Aurelio Giron Jr.

REASON FOR CHANGE:
Lead land length changed

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100768
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: ± 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice.
Contact technical support at <https://www.analog.com/en/support> for further questions.

TITLE:

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[K3255Y+12C] SAWN QFN-CU

APPROVAL

KAI LIU

DOCUMENT CONTROL NO.

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REVISION HISTORY

[illegible]

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